

RJ45C5E R1D 3.2N4G/Y TY**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com



The product range encompasses the following designs:

- 90°, lying (horizontal) and 180°, standing (vertical)
- latch up / latch down
- THT, THR or SMD soldering processes
- Wide range of different design types, also with integrated LEDs and shield contact tabs
- Performance category Cat. 3 to Cat. 6
- Packed either in a tray (TY) or on a roll (tape-on-reel, RL)
- Compatible with modular RJ45 connector according to ANSI / TIA-1096-A and IEC 60603
- Dielectric strength ≥ 1500 V AC RMS (2250 V AC peak value) according to IEEE 802.3
- Dielectric strength ≥ 1500 V AC (peak value) or ≥ 1500 V DC according to IEC 60603

Properties and advantages:

- Extended temperature range of -40°C to $+85^{\circ}\text{C}$ for maximum performance
- Reinforced gold layer (30 μm) for improved corrosion protection
- At least 0.3mm stand-off ensures a perfect soldering result

General ordering data

Version	PCB plug-in connector, RJ45 jacks, Cat. 5e, THT/THR solder connection, 90°, Latch option: bottom, LED: Yes, Number of poles: 8, Tray (manual assembly)
Order No.	2613200000
Type	RJ45C5E R1D 3.2N4G/Y TY
GTIN (EAN)	4050118623802
Qty.	600 pc(s).
Packaging	Tray (manual assembly)

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Technical data

Dimensions and weights

Depth	21.27 mm	Depth (inches)	0.837 inch
Height	13.45 mm	Height (inches)	0.53 inch
Height of lowest version	13.45 mm	Width	15.88 mm
Width (inches)	0.625 inch	Net weight	1.615 g

System specifications

Category	Cat. 5e	LED	Yes
Latch option	bottom	Mounting onto the PCB	THT/THR solder connection
Number of poles	8	Outgoing elbow	90°
Performance-Category	Cat. 5e	Pitch in inches (P)	0.05 "
Pitch in mm (P)	1.27 mm	Plugging cycles	750
Product family	OMNIMATE Data - RJ45 modular jack	Protection degree	IP20
Shield surface	nickel-plated	Shielding	Yes
Solder pin dimensions	Octagonal	Solder pin length (l)	3.2 mm
Soldering process	Reflow soldering, Manual soldering, Wave soldering	Tolerance of solder pin position	± 0.1 mm
Type of connection	Solder connection		

Electrical properties

Dielectric strength, contact / contact	1000 V DC	Dielectric strength, contact / shield	1500 V DC
Insulation strength	≥ 500 MΩ	PoE / PoE+	conforming to IEEE 802.3at
Rated voltage	125 V		

Material data

Insulating material	PA 9T	Colour	black
Colour chart (similar)	RAL 9011	Insulation strength	≥ 500 MΩ
Moisture Level (MSL)	1	UL 94 flammability rating	V-0
Contact material	Cu-alloy	Contact surface	Gold over nickel
Storage temperature, min.	-40 °C	Storage temperature, max.	85 °C
Operating temperature, min.	-40 °C	Operating temperature, max.	85 °C

Packing

Packaging	Tray (manual assembly)	VPE length	406 mm
VPE width	313 mm	VPE height	149 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ETIM 9.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01
ECLASS 12.0	27-46-02-01	ECLASS 13.0	27-46-02-01
ECLASS 14.0	27-46-02-01		

Environmental Product Compliance

REACH SVHC	/
RoHS Compliance Status	Compliant without exemption

Creation date August 29, 2024 5:09:00 PM CEST

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Technical data

Approvals

ROHS

Conform

Downloads

Approval/Certificate/Document of Con-
formity

[Certificate of Compliance](#)

Catalogues

[Catalogues in PDF-format](#)

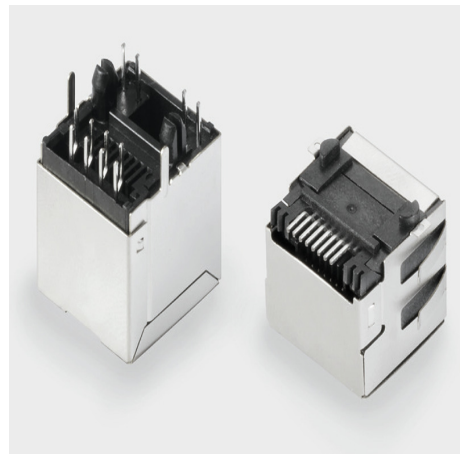
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Drawings

Product benefits

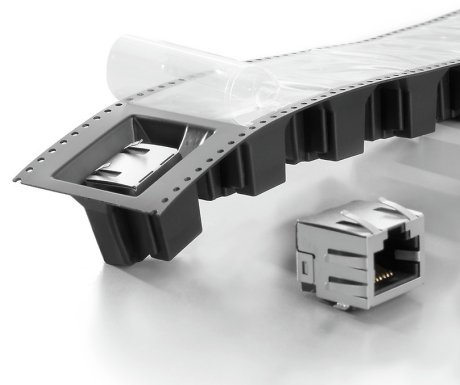


Product benefits



Suitable for all soldering processes
SMT, THT or THR

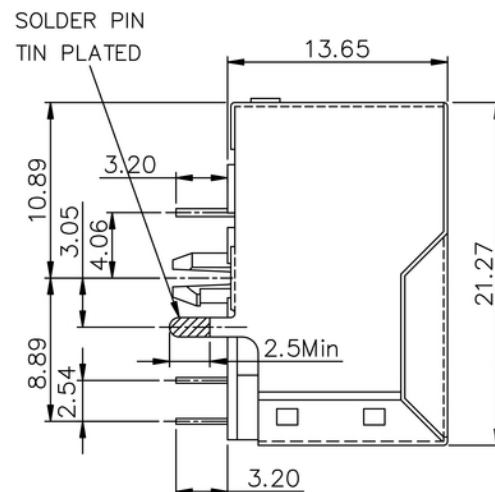
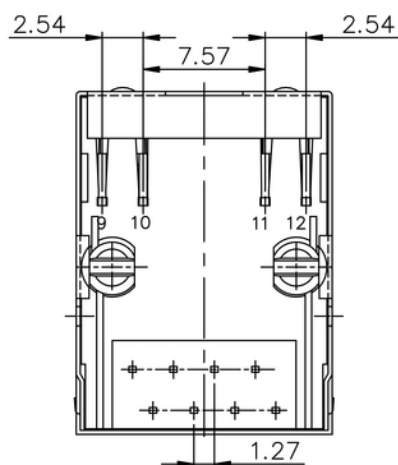
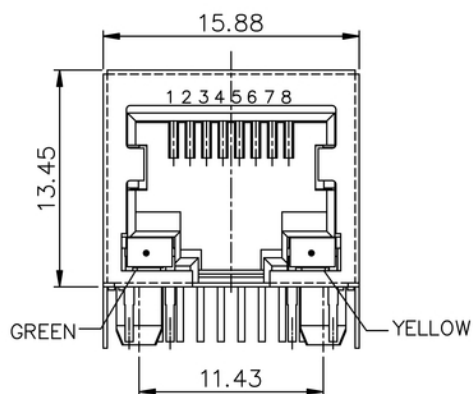
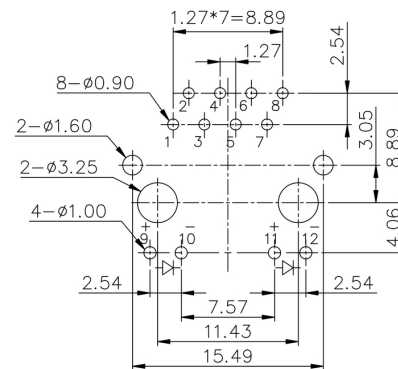
Product benefits



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Drawings

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Drawings

RJ45	G1	R	1	U	3.2	E	4	GY/GY	TY	RJ45G1 R1U 3.2E4GY/GY TY

Recommended wave soldering profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.